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SIEWERT et al.(10) **Pub. No.: US 2022/0369497 A1**(43) **Pub. Date: Nov. 17, 2022**(54) **ARRANGEMENT MADE UP OF COOLING
DEVICE AND COOLING ARTICLE**(52) **U.S. CL.**
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H05K 7/20 (2006.01)(57) **ABSTRACT**

An arrangement having a cooling device for dissipating heat from articles to be cooled which has at least one heat sink that has a heat absorption surface composed of metal and that is intended to absorb heat from one or more articles to be cooled, and also a cooling fluid chamber for accommodating cooling fluid to which the heat absorbed by the heat sink can be transferred, and having at least one article to be cooled which has a preferably planar heat emission surface composed of metal. To optimize the heat conduction between the heat sink and the article to be cooled, the heat absorption surface of the heat sink bears directly against the heat emission surface of the article to be cooled without an intermediate layer composed of air-displacing material, or, if necessary, with the use of an intermediate layer composed of air-displacing material that is thin.

